

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SATOSHI TOKUNAGA	02/18/2021
TOMOO KASHIWA	02/19/2021
RECEIVING PARTY DATA	
Name:	TAIYO YUDEN CO., LTD.
Street Address:	7-19 KYOBASHI 2-CHOME
Internal Address:	CHUO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	104-0031
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18079287
CORRESPONDENCE DATA	
Fax Number:	(703)770-7901
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7037707900
Email:	docket_ip@pillsburylaw.com, satoko.inoue@pillsburylaw.com, barbie.beavers@pillsburylaw.com,
Correspondent Name:	PILLSBURY WINTHROP SHAW PITTMAN LLP
Address Line 1:	P.O. BOX 10500
Address Line 4:	MCLEAN, VIRGINIA 22102
ATTORNEY DOCKET NUMBER:	083146-0572767
NAME OF SUBMITTER:	BARBIE BEAVERS
SIGNATURE:	/BARBIE BEAVERS/
DATE SIGNED:	12/12/2022
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
source=DECLARATIONANDASSIGNMENT#page1.tif	
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**DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT**

Title of Invention: **COIL COMPONENT, CIRCUIT BOARD, AND ELECTRONIC DEVICE**

As a below named inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

United States application or PCT international application number _____ filed on
_____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, the undersigned inventor(s) (hereinafter "Assignor"), has/have made an invention entitled "**COIL COMPONENT, CIRCUIT BOARD, AND ELECTRONIC DEVICE**" disclosed in the above-identified patent application and further identified by the Attorney Docket Number provided in the header of this document, and

WHEREAS, **TAIYO YUDEN CO., LTD.** (hereinafter "Assignee"), having a place of business at 7-19 Kyobashi 2-chome, Chuo-ku, Tokyo, 104-0031, JAPAN, is desirous of acquiring the entire right, title and interest in and to the aforesaid invention, application and all Letters Patent of the United States or any foreign country, including continuations, continuations-in-part, reissues, reexaminations, extensions, substitutes, and divisions which may be granted therefor;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said Assignor, by these presents do sell, assign and transfer unto Assignee, its successors, legal representatives and assigns, the full and exclusive right in and to the said invention as described in the said application, and in and to any Letters Patent of the United States or any foreign country, including continuations, continuations-in-part, reissues, reexaminations, extensions, substitutes, and divisions which may be granted therefor and all rights to claim priority on the basis of said application; and I further grant to Assignee the sole right to sue and collect damages for past infringement;

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks or any other proper officer or agency of any country to issue all said Letters Patent to said Assignee;

AND I HEREBY warrant and covenant that I have the full right to convey the entire interest herein

assigned and that I have not executed and will not execute any instrument or assignment in conflict herewith;

AND I HEREBY agree to communicate to said Assignee or its representatives any facts known to me respecting said invention, to execute all divisional, continuation, reissue, reexamination, extension, substitute, and foreign applications, sign all lawful documents and make all rightful oaths and declarations relating to said invention, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors, legal representatives or assigns, and to testify in any judicial or administrative proceeding and generally do everything possible to aid the said Assignee to obtain and enforce said Letters Patent in the United States or any foreign country when requested so to do by said Assignee.

(1) Legal Name of Inventor: Satoshi TOKUNAGA

Signature: Satoshi Tokunaga Date: 2021 / 2 / 18

Citizenship: JAPAN

(2) Legal Name of Inventor: Tomoo KASHIWA

Signature: Tomoo Kashiwa Date: 2021 / 2 / 19

Citizenship: JAPAN

[IF MORE INVENTORS, ADDITIONAL SIGNATURE PAGE(S) FOLLOWS]